Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

REMINDERS

Product Information in this Catalog

Product information in this catalog is as of January 2021. All of the contents specified herein and production status of the products listed in this catalog are subject to change without notice due to technical improvement of our products, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

Approval of Product Specifications

Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available. When using our products, please be sure to approve our product specifications or make a written agreement on the product specification with TAIYO YUDEN in advance.

Pre-Evaluation in the Actual Equipment and Conditions

Please conduct validation and verification of our products in actual conditions of mounting and operating environment before using our products.

Limited Application

1. Equipment Intended for Use

The products listed in this catalog are intended for generalpurpose and standard use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC) and other equipment specified in this catalog or the individual product specification sheets.

TAIYO YUDEN has the line-up of the products intended for use in automotive electronic equipment, telecommunications infrastructure and industrial equipment, or medical devices classified as GHTF Classes A to C (Japan Classes I to III). Therefore, when using our products for these equipment, please check available applications specified in this catalog or the individual product specification sheets and use the corresponding products.

2. Equipment Requiring Inquiry

Please be sure to contact TAIYO YUDEN for further information before using the products listed in this catalog for the following equipment (excluding intended equipment as specified in this catalog or the individual product specification sheets) which may cause loss of human life, bodily injury, serious property damage and/or serious public impact due to a failure or defect of the products and/or malfunction attributed thereto.

- (1) Transportation equipment (automotive powertrain control system, train control system, and ship control system, etc.)
- (2) Traffic signal equipment
- (3) Disaster prevention equipment, crime prevention equipment
- (4) Medical devices classified as GHTF Class C (Japan Class III)
- (5) Highly public information network equipment, dataprocessing equipment (telephone exchange, and base station, etc.)
- (6) Any other equipment requiring high levels of quality and/or reliability equal to the equipment listed above

3. Equipment Prohibited for Use

Please do not incorporate our products into the following equipment requiring extremely high levels of safety and/or reliability.

- (1) Aerospace equipment (artificial satellite, rocket, etc.)
- (2) Aviation equipment *1
- (3) Medical devices classified as GHTF Class D (Japan Class IV), implantable medical devices *²

- (4) Power generation control equipment (nuclear power, hydroelectric power, thermal power plant control system, etc.)
- (5) Undersea equipment (submarine repeating equipment, underwater work equipment, etc.)
- (6) Military equipment
- (7) Any other equipment requiring extremely high levels of safety and/or reliability equal to the equipment listed above

*Notes:

- There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.
- Implantable medical devices contain not only internal unit which is implanted in a body, but also external unit which is connected to the internal unit.

4. Limitation of Liability

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment that is not intended for use by TAIYO YUDEN, or any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

Safety Design

When using our products for high safety and/or reliability-required equipment or circuits, please fully perform safety and/or reliability evaluation. In addition, please install (i) systems equipped with a protection circuit and a protection device and/or (ii) systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault for a failsafe design to ensure safety.

Intellectual Property Rights

Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.

Limited Warranty

Please note that the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a failure or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement.

TAIYO YUDEN's Official Sales Channel

The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

Caution for Export

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

for General Electronic Equipment

WIRE-WOUND CHIP INDUCTORS FOR SIGNAL LINES (LB SERIES M TYPE)

PARTS NUMB	ER		
L B M /	△ 2 0 1 6 ②	T 1 0 0 J △ ③ ④ ⑤ ⑥	
①Series name			
Code	Series	aname	
LBM△	Wound chip induc	ctor for signal line	
②Dimensions(L	×W)		
Code	Type(inch)	Dimensions (L × W) [mm]	
2016	2016(0806)	2.0 × 1.6	
③Packaging			
Code	Packaging		
Т	Taping		

*	Operating	Temp :-40~+1	105°C (Includi	ing self-generate	(tead b

 $\Delta =$ Blank space

④Nominal inductance				
Code (example)	Nominal inductance [μ H]			
R12	0.12			
1 R0	1.0			
100	10			
101	100			

ℜR=Decimal point

(5)Inductance tolerance

Code	Inductance tolerance	
J	$\pm 5\%$	

⑥Internal code

STANDARD EXTERNAL DIMENSIONS / STANDARD QUANTITY

Recommended Land Patterns Surface Mounting Mounting and soldering conditions should be checked beforehand. Applicable soldering process to these products is reflow soldering only. Type A B C LBM 2016 0.6 1.0 1.8 Unit:mm						A A	c				
Туре	L	W		т	е	Standa Paper tape	rd quant			ed tape	
LBM 2016	2.0±0.2 (0.08±0.008)	1.6±0.2 (0.063±0.008)			0.5±0.2 (0.02±0.008)				200		
	•	•	•	•		•		Jnit : I	mm (in	ch)	

REFLOW

for General Electronic Equipment

PARTS NUMBER

Parts number	EHS	Nominal inductance [µ H]	Inductance tolerance	Q (min.)	Self-resonant frequency [MHz] (min.)	DC Resistance $[\Omega](\pm 30\%)$	Rated current [mA] (max.)	Measuring frequency [MHz]
BM 2016TR12J	RoHS	0.12	±5%	30	600	0.13	610	25.2
BM 2016TR15J	RoHS	0.15	±5%	30	550	0.15	570	25.2
BM 2016TR18J	RoHS	0.18	±5%	30	500	0.15	560	25.2
LBM 2016TR22J	RoHS	0.22	±5%	30	450	0.20	520	25.2
_BM 2016TR27J	RoHS	0.27	±5%	30	425	0.21	510	25.2
_BM 2016TR33J	RoHS	0.33	±5%	30	400	0.21	490	25.2
_BM 2016TR39J	RoHS	0.39	±5%	30	375	0.26	440	25.2
_BM 2016TR47J	RoHS	0.47	±5%	30	350	0.26	430	25.2
_BM 2016TR56J	RoHS	0.56	±5%	30	300	0.29	410	25.2
_BM 2016TR68J	RoHS	0.68	±5%	30	270	0.32	400	25.2
_BM 2016TR82J	RoHS	0.82	±5%	30	250	0.34	390	25.2
LBM 2016T1R0J	RoHS	1.0	±5%	30	220	0.38	385	7.96
LBM 2016T1R2J	RoHS	1.2	±5%	30	180	0.41	370	7.96
_BM 2016T1R5J	RoHS	1.5	±5%	30	135	0.47	350	7.96
LBM 2016T1R8J	RoHS	1.8	±5%	30	100	0.48	345	7.96
_BM 2016T2R2J	RoHS	2.2	±5%	30	75	0.54	340	7.96
_BM 2016T2R7J	RoHS	2.7	±5%	30	55	0.59	310	7.96
LBM 2016T3R3J	RoHS	3.3	±5%	30	48	0.68	290	7.96
LBM 2016T3R9J	RoHS	3.9	±5%	30	43	0.74	275	7.96
LBM 2016T4R7J	RoHS	4.7	±5%	30	40	0.78	270	7.96
_BM 2016T5R6J	RoHS	5.6	±5%	25	36	0.88	255	7.96
LBM 2016T6R8J	RoHS	6.8	±5%	25	33	0.97	240	7.96
LBM 2016T8R2J	RoHS	8.2	±5%	25	30	1.1	225	7.96
LBM 2016T100J	RoHS	10	±5%	25	27	1.2	215	2.52
LBM 2016T120J	RoHS	12	±5%	25	23	1.4	200	2.52
LBM 2016T150J	RoHS	15	±5%	25	20	1.5	190	2.52
LBM 2016T180J	RoHS	18	±5%	25	18	2.5	150	2.52
_BM 2016T220J	RoHS	22	±5%	25	17	2.8	140	2.52
_BM 2016T270J	RoHS	27	±5%	25	16	3.2	130	2.52
_BM 2016T330J	RoHS	33	±5%	25	15	3.6	125	2.52
LBM 2016T390J	RoHS	39	±5%	20	14	3.9	120	2.52
_BM 2016T470J	RoHS	47	±5%	20	13	4.1	115	2.52
_BM 2016T560J	RoHS	56	±5%	20	12	5.9	95	2.52
_BM 2016T680J	RoHS	68	±5%	20	11	7.0	90	2.52
_BM 2016T820J	RoHS	82	±5%	20	10	7.7	85	2.52
_BM 2016T101J	RoHS	100	±5%	15	9.0	8.0	80	0.796
_BM 2016T151J	RoHS	150	±5%	15	6.5	13.5	69	0.796
_BM 2016T181J	RoHS	180	±5%	15	6.0	15	67	0.796
BM 2016T221J	RoHS	220	±5%	15	5.5	18	65	0.796

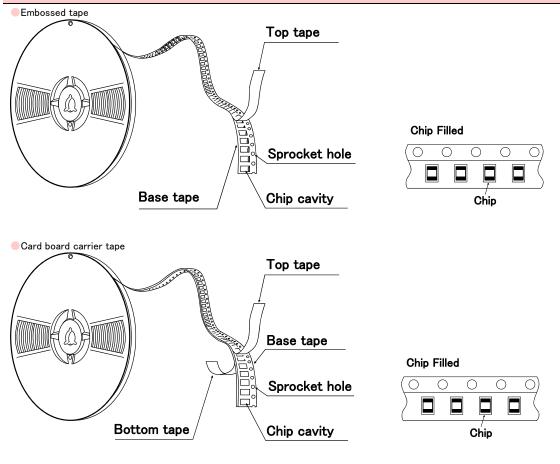
X)Rated Current : The maximum DC value having inductance decrease within 10 % and temperature increase within 20 degC by the application of DC bias.

WIRE-WOUND CHIP INDUCTORS (LB SERIES), WIRE-WOUND CHIP POWER INDUCTORS (CB SERIES), WIRE-WOUND CHIP INDUCTORS FOR SIGNAL LINES (LB SERIES M TYPE)

PACKAGING

①Minimum Quantity				
	Standard Qu	antity [pcs]		
Туре	Paper Tape	Embossed Tape		
LB C3225	_	1000		
CB C3225		1000		
LB 3218	—	2000		
LB R2518				
LB C2518				
LB 2518	-	2000		
CB 2518				
CB C2518				
LBM2016				
LB C2016				
LB 2016	—	2000		
CB 2016				
CB C2016				
LB 2012				
LB C2012				
LB R2012	—	3000		
CB 2012				
CB C2012				
CB L2012	4000	_		
LB 1608	4000	-		
LBMF1608	_	3000		
CBMF1608		0000		

2 Tape material



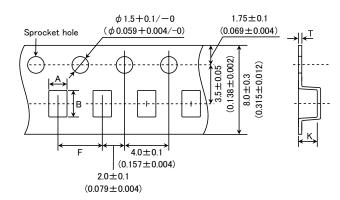
This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

i_wound_CB_LB_pack_e-E05R01



③Taping Dimensions

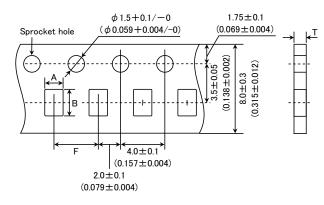
Embossed Tape (0.315 inches wide)



T	Chip	Chip cavity		Tape th	ickness
Туре	А	В	F	Т	К
LBM2016	1.75 ± 0.1 (0.069 ± 0.004)	2.1±0.1 (0.083±0.004)	4.0 ± 0.1 (0.157 ± 0.004)	0.3±0.05 (0.012±0.002)	1.9max. (0.075max.)
LB C3225 CB C3225	2.8±0.1 (0.110±0.004)	3.5 ± 0.1 (0.138 ± 0.004)	4.0±0.1 (0.157±0.004)	0.3±0.05 (0.012±0.002)	4.0max. (0.157max.)
LB 3218	2.1±0.1 (0.083±0.004)	3.5 ± 0.1 (0.138 ± 0.004)	4.0±0.1 (0.157±0.004)	0.3±0.05 (0.012±0.002)	2.2max. (0.087max.)
LB 2518 CB 2518 LB C2518 CB C2518 LB R2518	2.15±0.1 (0.085±0.004)	2.7±0.1 (0.106±0.004)	4.0±0.1 (0.157±0.004)	0.3±0.05 (0.012±0.002)	2.2max. (0.087max.)
LB 2016 CB 2016 LB C2016 CB C2016	1.75±0.1 (0.069±0.004)	2.1±0.1 (0.083±0.004)	4.0±0.1 (0.157±0.004)	0.3±0.05 (0.012±0.002)	1.9max. (0.075max.)
LB 2012 CB 2012 LB C2012 CB C2012 LB R2012	1.45±0.1 (0.057±0.004)	2.25±0.1 (0.089±0.004)	4.0±0.1 (0.157±0.004)	0.25±0.05 (0.010±0.002)	1.45max. (0.057max.)
LBMF1608 CBMF1608	$ \begin{array}{r} 1.1 \pm 0.1 \\ (0.043 \pm 0.004) \end{array} $	1.9 ± 0.1 (0.075 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)	0.25±0.05 (0.010±0.002)	1.2max. (0.047max.)

Unit:mm(inch)

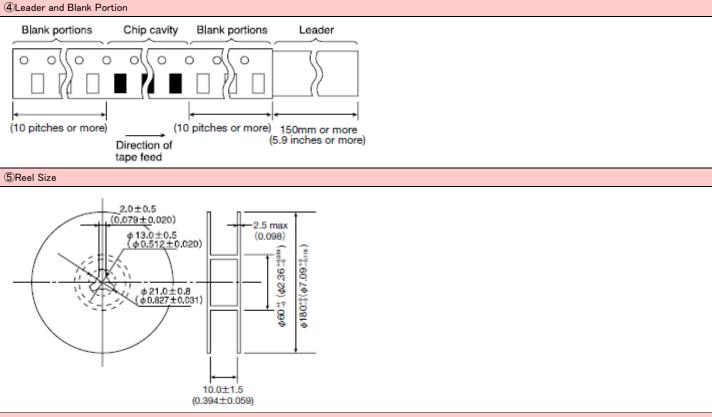
Card board carrier tape (0.315 inches wide)



Tune	Chip	cavity	Insertion pitch	Tape thickness
Туре	A	В	F	Т
OB 1 2012	1.55 ± 0.1	2.3±0.1	4.0±0.1	1.1max.
CB L2012	(0.061 ± 0.004)	(0.091 ± 0.004)	(0.157 ± 0.004)	(0.043max.)
LB 1608	1.0 ± 0.1	1.8±0.1	4.0±0.1	1.1max.
LB 1608	(0.039 ± 0.004)	(0.071 ± 0.004)	(0.157 ± 0.004)	(0.043max.)
				l lucit : mama (im ala)

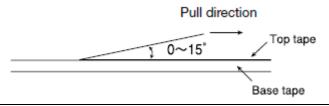
Unit:mm(inch)





6 Top Tape Strength

The top tape requires a peel-off force 0.2 to 0.7N in the direction of the arrow as illustrated below.



WIRE-WOUND CHIP INDUCTORS (LB SERIES), WIRE-WOUND CHIP POWER INDUCTORS (CB SERIES), WIRE-WOUND CHIP INDUCTORS FOR SIGNAL LINES (LB SERIES M TYPE)

RELIABILITY DATA

1.Operating temperature Range				
	LB, LBC, LBR, LBMF Series			
Specified Value	CB, CBC, CBL, CBMF Series	-40 ~ $+105^{\circ}$ C (Including self-generated heat)		
	LBM Series			
	LDM Series			

2. Storage Tempera	2. Storage Temperature Range (after soldering)			
	LB, LBC, LBR, LBMF Series			
Specified Value	CB, CBC, CBL, CBMF Series	-40~+85°C		
	LBM Series			
Test Methods and	LB, CB Series:			
Remarks	Please refer the term of "7. storage conditions" in precautions.			

3.Rated Current					
	LB, LBC, LBR, LBMF Series				
Specified Value	CB, CBC, CBL, CBMF Series	Within the specified tolerance			
	LBM Series				

4.Inductance	4.Inductance				
	LB, LBC, LBR, LBMF Series				
Specified Value	CB, CBC, CBL, CBMF Series	Within the specified tolerance			
	LBM Series				
Test Methods and Remarks	LB·LBC·LBR·CB·CBC·CBL·LBMF·CBMF·LBM Series Measuring equipment :LCR Mater (HP4285A or its equency) Measuring frequency : Specified frequency	quivalent)			

5.Q			
	LB, LBC, LBR, LBMF Series		_
Specified Value	CB, CBC, CBL, CBMF Series		
	LBM Series		Within the specified tolerance
Test Methods and Remarks	LBM Series Measuring equipment : LCR Mater (HP4285A or its e		uivalent)
	Measuring frequency : Specified frequency		

6.DC Resisitance			
	LB, LBC, LBR, LBMF Series	Within the specified tolerance	
Specified Value	CB, CBC, CBL, CBMF Series		
	LBM Series		
Test Methods and Remarks	Measuring equipment : DC Ohmmeter (HIOKI 3227 or its equivalent)		

7.Self-Resonant Frequency			
	LB, LBC, LBR, LBMF Series		
Specified Value	CB, CBC, CBL, CBMF Series	Within the specified tolerance	
	LBM Series		
Test Methods and Remarks	Measuring equipment : Impedance analyzer (HP4291A or its equivalent)		



8.Temperature Char	8.Temperature Characteristic				
	LBM2016				Inductance change : Within±5%
	LB1608	LB2012	LBR2012	CB2012	
	CBL2012	LB2016	CB2016	LB2518	Inductance change : Within±20%
Specified Value	LBR2518	CB2518	LBC3225	CBC3225	
	LBMF1608	CBMF1608	LBC2016	CBC2016	
	LBC2518	CBC2518	LB3218		Inductance change : Within±25%
	LBC2012	CBC2012			Inductance change : Within±35%
Test Methods and Remarks	Based on the inductance at 20°C and Measured at the ambient of $-40^{\circ}C \sim +85^{\circ}C$.				

9.Rasistance to Flex	xure of Substrate		
	LB, LBC, LBR, LBMF Series	No damage.	
Specified Value	CB, CBC, CBL, CBMF Series		
	LBM Series		
	Warp : 2mm(LB·LBC·LBR·CB·CBC·CBL·LBM·LBMF·CBMF Series)		
	Test substrate : Glass epoxy-resin substrate		
	Thickness : 0.8mm(LB1608·LBMF1608·CBMF1608)		
	: 1.0mm(Others)		
	Pressing jig		
Test Methods and			
Remarks	R340		
	Board		
	R5 45±2mm 45±2mm		

10.Body Strength		
	LB, LBC, LBR, LBMF Series	
Specified Value	CB, CBC, CBL, CBMF Series	No damage.
	LBM Series	
Test Methods and Remarks	LB+LBC+LBR+CB+CBC+CBL+LBM Applied force : 10N Duration : 10sec. LB1608+LBMF1608+CBMF1608 Applied force : 5N Duration : 10sec.	

11.Adhesion of term	ninal electrode		
	LB, LBC, LBR, LBMF Series		
Specified Value	CB, CBC, CBL, CBMF Series		No abnormality.
	LBM Series		
Test Methods and Remarks	LB+LBC+LBR+CB+CBC+CBL+LBM+LBMF+CBMF Applied force : 10N to X and Y directions Duration : 5 sec. Test substrate : Printed board LB1608+CBMF1608+LBMF1608 Applied force : 5N to X and Y directions Duration : 5 sec. Test substrate : Printed board		



12.Resistance to vil	oration			
	LB, LBC, LBR, LBMF Series			Inductance change : Within±10%
Specified Value	CB, CBC, CBL, CBMF Series			No significant abnormality in appearance.
	LBM Series			Inductance change : Within±5% No significant abnormality in appearance.
Test Methods and Remarks	Vibration Frequency Total Amplitude Sweeping Method Time			eration 196m/s2) in. n each X, Y, and Z axis.
	Recovery : At least 2 hrs of recovery under the standard condition after the			ondition after the test, followed by the measurement within 48 hrs.

 13.Drop test

 Specified Value
 LB, LBC, LBR, LBMF Series

 CB, CBC, CBL, CBMF Series

 LBM Series

14.Solderability		
	LB, LBC, LBR, LBMF Series	
Specified Value	CB, CBC, CBL, CBMF Series	At least 90% of surface of terminal electrode is covered by new
	LBM Series	
Test Methods and Remarks	LB·LBC·LBR·CB·CBC·CBL·LBM·LBMF·CB Solder temperature : 245±5°C Duration : 5±0.5sec Flux : Methanol solution with	3MF: vith 25% of colophony

15.Resistance to so	15.Resistance to soldering				
	LB, LBC, LBR, LBMF Series	Inductance change : Within±10%			
Specified Value	CB, CBC, CBL, CBMF Series				
	LBM Series	Inductance change : Within $\pm 5\%$			
Test Methods and Remarks	LB·LBC·LBR·CB·CBC·CBL·LBM·LBMF·CBMF: 3 times of reflow oven at 230°C MIN for 40sec. with peak temperature at 260 °C for 5sec. Recovery : At least 2 hrs of recovery under the standard condition after the test, followed by the measurement within 48 hrs.				

16.Resisitance to solvent				
Specified Value	LB, LBC, LBR, LBMF Series			
	CB, CBC, CBL, CBMF Series		_	
	LBM Series			
Test Methods and Remarks	Solvent temperature: Room temperatureType of solvent: Isopropyl alcoholCleaning conditions: 90s. Immersion and cleaning.			

17.Thermal shock				
	LB, LBC, LBR, LBMF Series			Inductance change : Within±10% No significant abnormality in appearance.
Specified Value	CB, CBC, CBL, CBMF Series			
	LBM Series			
Test Methods and Remarks		·LBR·CB·CBC·CBL·LBM·L		ance is measured after 100 cycles of the following conditions
Remarks	The given sample is soldered to the board and then its Inductance is measured after 100cycles of the following conditions. Conditions of 1 cycle			
	Step	Temperature (°C)	Duration (min)	
	1 -40±3 30±3		30±3	
	2	Room temperature	Within 3	
	3	+85±2	30±3	
	4	Room temperature	Within 3	
	Recover	ry : At least 2 hrs of	recovery under the sta	ndard condition after the test, followed by the measurement within 48 hrs.



18.Damp heat life te	18.Damp heat life test				
	LB, LBC, LBR, LBMF Series		Inductance change : Within±10% No significant abnormality in appearance.		
Specified Value	CB, CBC, CBL, CBMF Series				
	LBM Series				
	Temperature	: 60±2°C			
Test Methods and	Humidity	: 90 ~ 95%RH			
Remarks	Duration	: 1000 hrs			
	Recovery	very : At least 2 hrs of recovery under the standard condition after the test, followed by the measurement within 48 hrs.			

19.Loading under da	imp heat life test		
	LB, LBC, LBR, LBMF Series		Inductance change : Within±10% No significant abnormality in appearance.
	CB, CBC, CBL, CBMF Series		
Specified Value	LBM Series		
Test Methods and	Temperature	: 60±2°C	
Remarks	Humidity	: 90~95%RH	
	Duration	: 1000 hrs	
	Applied current	: Rated current	
	Recovery	: At least 2 hrs of recovery under the st	andard condition after the test, followed by the measurement within 48 hrs.

20.High temperature	e life test		
	LB, LBC, LBR, LBMF Series		1
Specified Value	CB, CBC, CBL, CBMF Series		Inductance change : Within \pm 10% No significant abnormality in appearance.
	LBM Series		
Test Methods and Remarks	Temperature Duration Recovery	: 85±2°C : 1000 hrs : At least 2 hrs of recovery under the sta	ndard condition after the test, followed by the measurement within 48 hrs.

21.Loading at high t	21.Loading at high temperature life test		
Specified Value	LB, LBC, LBR, LBMF Series		Inductance change : Within±10% (LBC3225 Series : Within±20%) No significant abnormality in appearance.
·	CB, CBC, CBL, CBMF Series		
	LBM Series		
	Temperature	: 85±2°C	
Test Methods and	Duration	: 1000 hrs	
Remarks	Applied current	: Rated current	
	Recovery : At least 2 hrs of recovery under the		andard condition after the test, followed by the measurement within 48 hrs.

22.Low temperature	e life test		
Specified Value	LB, LBC, LBR, LBMF Series		Inductance change : Within±10% No significant abnormality in appearance.
	CB, CBC, CBL, CBMF Series		
	LBM Series		
Test Methods and Remarks	Temperature Duration Recovery	: −40±2°C : 1000 hrs : At least 2 hrs of recovery under the sta	andard condition after the test, followed by the measurement within 48 hrs.

23.Standard conditi	23.Standard condition			
Specified Value	LB, LBC, LBR, LBMF Series	Standard test conditions Unless specified, Ambient temperature is $20\pm15^\circ$ C and the Relative		
	CB, CBC, CBL, CBMF Series	 humidity is 65±20%. If there is any doubt about the test results, further measurement shall be had within the following limits: Ambient Temperature: 20±2°C Relative humidity: 65±5% Inductance value is based on our standard measurement systems. 		
	LBM Series			

WIRE-WOUND CHIP INDUCTORS (LB SERIES), WIRE-WOUND CHIP POWER INDUCTORS (CB SERIES), WIRE-WOUND CHIP INDUCTORS FOR SIGNAL LINES (LB SERIES M TYPE)

PRECAUTIONS

1. Circuit Design	
Precautions	 Operating environment The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance.

2. PCB Design	
Precautions	 Land pattern design Please contact any of our offices for a land pattern, and refer to a recommended land pattern of a right figure or specifications.
Technical considerations	PRECAUTIONS [Recommended Land Patterns] Surface Mounting • Mounting and soldering conditions should be checked beforehand. • Applicable soldering process to those products is reflow soldering only.

3. Considerations	3. Considerations for automatic placement		
Precautions	 Adjustment of mounting machine 1. Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2. Mounting and soldering conditions should be checked beforehand. 		
Technical considerations	1. When installing products, care should be taken not to apply distortion stress as it may deform the products.		

4. Soldering			
Precautions	 Reflow soldering(LB and CB Types) For reflow soldering with either leaded or lead-free solder, the profile specified in "point for controlling" is recommended. Recommended conditions for using a soldering iron Put the soldering iron on the land-pattern. Soldering iron's temperature - Below 350°C Duration-3 seconds or less. The soldering should not come in contact with inductor directly. 		
Technical considerations	 Reflow soldering(LB and CB Types) Reflow profile Reflow profile Reflow profile Sec max Peak: 200 90±30sec 230°C min Heating Time [sec] Recommended conditions for using a soldering iron Components can be damaged by excessive heat where soldering conditions exceed the specified range. 		

5. Cleaning	
Precautions	♦ Cleaning conditions Washing by supersonic waves shall be avoided.
Technical considerations	♦Cleaning conditions If washed by supersonic waves, the products might be broken.



6. Handling	
Precautions	 Handling Keep the inductors away from all magnets and magnetic objects. Breakaway PC boards (splitting along perforations) When splitting the PC board after mounting inductors, care should be taken not to give any stresses of deflection or twisting to the board. Board separation should not be done manually, but by using the appropriate devices. Mechanical considerations Please do not give the inductors any excessive mechanical shocks.
Technical considerations	 Handling 1. There is a case that a characteristic varies with magnetic influence. Breakaway PC boards (splitting along perforations) 1. Planning pattern configurations and the position of products should be carefully performed to minimize stress. Mechanical considerations 1. There is a case to be damaged by a mechanical shock.

Precautions	♦ Storage
	 To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. Recommended conditions Ambient temperature : 0~40°C Humidity : Below 70% RH The ambient temperature must be kept below 30°C. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, product should be used within 6 months from the time of delivery. In case of storage over 6 months, solderability shall be checked before actual usage.
Technical considerations	 Storage 1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrode and deterioration of taping/packaging materials may take place.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Taiyo Yuden:

LBM2016T100J	LBM2016T101J	LBM2016T120J	LBM2016T150J	LBM2016T180J	LBM2016T1R0J				
LBM2016T1R2J	LBM2016T1R5J	LBM2016T1R8J	LBM2016T220J	LBM2016T270J	LBM2016T2R2J				
LBM2016T2R7J	LBM2016T330J	LBM2016T390J	LBM2016T3R3J	LBM2016T3R9J	LBM2016T470J				
LBM2016T4R7J	LBM2016T560J	LBM2016T5R6J	LBM2016T680J	LBM2016T6R8J	LBM2016T820J				
LBM2016T8R2J	LBM2016TR12J	LBM2016TR15J	LBM2016TR18J	LBM2016TR22J	LBM2016TR27J				
LBM2016TR33J	LBM2016TR39J	LBM2016TR47J	LBM2016TR56J	LBM2016TR68J	LBM2016TR82J				
LBM2016TR68JV LBM2016T221J LBM2016T101J8									